

Page 1, Line 32, before this line insert the following paragraph
heading.

SUMMARY OF THE INVENTION

Page 3, Line 26, before this line insert the following paragraph
heading:

BRIEF DESCRIPTION OF THE DRAWING

Page 3, Line 34, before this line insert the following paragraph
heading:

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

IN THE CLAIMS

(APPLICATION PAGES 6-7)

Before claim 1, change "Patent Claims" to --I CLAIM:--

Please cancel claims 1-10 without prejudice or disclaimer of the
subject matter therein and substitute new claims 11-20 therefor:

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11. (new) A light source comprising a
large number of light-emitting diodes, wherein the light-emitting
diodes (7) are mounted alongside one another on one face of a

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flexible printed circuit (4), and are electrically conductively connected to conductor tracks (5) on the flexible printed circuit (4).

Cont

2. (new) The light source as claimed in claim 11, wherein the flexible printed circuit (4) is mounted with that face which is opposite the light-emitting diodes (7) on a stable mounting board (2), for heat dissipation.

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13. (new) The light source as claimed in claim 12, wherein the mounting board (2) is composed of thermally conductive material.

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14. (new) The light source as claimed in claim 13, wherein the mounting board (2) is connected to a heat sink or is in form of a heat sink.

15. (new) The light source as claimed in claim 12, wherein the flexible printed circuit board (4) is connected to the mounting board (2) by a thermally conductive adhesive or a thermally conductive adhesion layer.

16. (new) The light source as claimed in claim 11, wherein the conductor tracks (9) end in contact pads (10) on the flexible printed circuit (4), with lines (8) which

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originate from the light-emitting diodes (7) making electrically conductive contact with the contact pads (10).

17. (new) The light source as claimed in claim 16, wherein at least one of the light-emitting diodes (7) is or are integrated in a semiconductor chip, and the semiconductor chip has a corresponding number of contact pads, which are electrically conductively connected to the corresponding contact pads (10) on the flexible printed circuit (4).

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18. (new) The light source as claimed in claim 17, wherein the electrically conductive connections are produced via wires which are connected to the contact pads on the flexible printed circuit and the semiconductor chip by soldering, bonding or adhesive bonding.

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19. (new) The light source as claimed in claim 11, wherein the light-emitting diodes (7) are arranged in an encapsulation compound (11).

20. (new) The light source as claimed in claim 19, wherein the encapsulation compound (11) extends as far as a light outlet surface of the light-emitting diodes (7).